#### Notification about the transfer of the semiconductor business

The semiconductor business of Panasonic Corporation was transferred on September 1, 2020 to Nuvoton Technology Corporation (hereinafter referred to as "Nuvoton"). Accordingly, Panasonic Semiconductor Solutions Co., Ltd. became under the umbrella of the Nuvoton Group, with the new name of Nuvoton Technology Corporation Japan (hereinafter referred to as "NTCJ").

In accordance with this transfer, semiconductor products will be handled as NTCJ-made products after September 1, 2020. However, such products will be continuously sold through Panasonic Corporation.

Publisher of this Document is NTCJ.

If you would find description "Panasonic" or "Panasonic semiconductor solutions", please replace it with NTCJ.

Except below description page
 "Request for your special attention and precautions in using the technical information and semiconductors described in this book"

Nuvoton Technology Corporation Japan

Doc No. TD4-EA-01877 Revision. 1

# Panasonic \_\_\_\_\_

### MIP2E3DMTSCF

種別/Type		シリコンMOS形集積回路/Silicon MOSFET Type Integrated Circuit									
用途/Application		スイッチング電源制御用/For a Switching Power Supply Control									
構造/Structure		CMOS形/CMOS Type									
等価	回路/Equivalen	t Circuit	添付図 5/	See Figu	re 5						
外形	外形/Out Line DIP7-A1-B				マーク記号/マーキング/Marking	MIP2E3D					
A. 絶:	対最大定格/Ab	solute Maximu	m Ratings (Ta	a=25℃±3	9°C)						
NO.	項目/Item			記号/ Symbol	定格/Ratings	単位/ Unit	備	考/No	te		
1	ドレイン電圧 DRAIN Voltage			VD	700	٧					
2	コントロール電圧 CONTROL Voltage			VC	10	V					
3	出力電流 Output Cur			ID	1. 15	А					
4	出力ピーク電 Output Pea	k Current		IDP	1. 60	Α					
5	コントロール「	Current		IC	0. 1	Α	-				
6	チャネル部温 Channel Tem 保存温度			Tch	150	°C					
7	休任温度 Channel Tem	perature		Tstg	−55 ~ +150	°C					
B. ¶	氢负的特性/Elec	ctrical Charact	eristics	;	則定条件/Measure Condition (Tc = :	25℃±3℃	)				
No.		項目/Item		記号/ Symbol	測定条件/Measure Condition (測定図-1 参照/See Figure 1)	Тур.	Lir Min.	mit Max.	Unit		
【コント	ロール機能/C	ontrol Function	ns: *は設計保	証項目/D	esign Guarantee Item]	•			<del></del>		
1	出力周波数 Output Frequer	псу		fosc	VC = VC (CNT) - 0.2V	100	90	110	kHz		
2	最大デューテ Maximum Duty			MAXDC	VC = VC (CNT) - 0.2V	69	66	72	%		
*3	PWMゲイン PWM Gain			GPWM		11			dB		
*4	スロープ補償 Slope Compens			m		40			mA/ μs		
【電源	/Supply: *は討		´Design Guarar	ntee Item]							
5	起動前動作電流 Before Auto-re			IC (SB)	VC < VC (ON) (2)	0.30	0.05	0.6	mA		
6	動作時電流 Operating Curr			IC (OP)	VC = VC (CNT) - 0.2V (2)	1.8	0.7	2.7	mA		
7	起動時コントロ Auto-restart T	hreshold Volta	ge	VC (ON)	S1=0PEN (2)	6.0	5.1	6.6	٧		
I .	停止時コントロ	- 11 地で雨	F I		01 0051	5.0	4.1	5.5	V		
8	UV Lockout Th 起動/停止ヒス	reshold Voltag	e \	VC (OFF)	S1=0PEN (2)	3.0	7.1	0.0			

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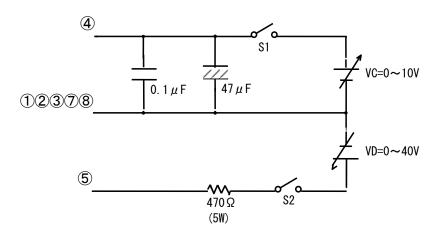
		記号/ Symbol	測定条件/Measure Condition (測定図-1 参照/See Figure 1)	Тур.	Limit		11.5
No.	項目/Item				Min.	Max.	Unit
電源	/Supply:*は設計保証項目/Design Gua	arantee Item】					
10	間欠動作時間比 Auto-restart duty cycle	TSW/TTIM	S1 = OPEN	2			%
11	間欠動作周波数 Auto-restart frequency	fTIM	S1 = OPEN	0.5			Hz
12	コントロール端子充電電流 CONTROL Pin Charging Current	IC (CHG)	VC = 0V VC = 5V	-1.9 -1.2	-2.5 -2.0	-1.2 -0.5	mA mA
13	コントロール電圧 CONTROL Pin Voltage	VC (CNT)		6.2	5.7	6.6	٧
*14	コントロール電圧ヒステリシス CONTROL Pin Voltage hysteresis	∠VC (CNT)		10			mV
15	最小ドレイン電圧 DRAIN Supply Voltage	VD (MIN)			36		٧
保護	機能/Circuit Protections:*は設計保証コ	頁目/Design G	uarantee Item]				
16	過電流保護検出 Self Protection Current Limit	ILIMIT		1.0	0.9	1.1	Α
*17	オン時ブランキング幅 Leading Edge Blanking Delay	ton (BLK)		0.25			μs
*18	過電流保護遅れ時間 Current Limit Delay	td (OCL)		0.1			με
*19	過熱保護電圧 Thermal Shutdown Temperature	ТОТР		140	130		°C
*20	ラッチリセット電圧 Power-up Reset Threshold Voltage	Vcreset	S2=0PEN	3.3	2.3	4.2	٧
出力 <sup>·</sup>	部/Output:*は設計保証項目/Design G	uarantee Item	]				
21	オン抵抗 On-State Resistance	RDS (ON)	ID = 0.2A (See Figure 2)	8.5		10.0	Ω
22	オフ時ドレイン端子リーク電流 Off-State Drain Pin Leakage Current	IDSS	VDS = 630V, VC = 6.5V	10		250	μA
23	ドレイン耐圧 Breakdown Voltage	VDSS	ID = 0.25mA, VC = 6.5V		700		٧
24	立ち上がり時間 Rise Time	tr	(1)	0.1			με
25	立ち下がり時間 Fall Time	tf	(1)	0.1			με
*26	熱抵抗 Thermal resistance (j-a)	Rth ( j-a )	エポキシ基板(3cm×3cm)実装時 Ta=25℃ Surface Mounted on Epoxy Board	90			°C/\

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【Figure 1:測定回路図/Measure Circuit】

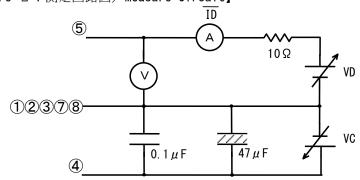


\*本測定回路図は、過電流保護検出値、出力特性の測定には使用できません。 This measurement circuit can't be useful for peak current and output characteristic measurement.

端子説明/Terminal explanation

③: Drain

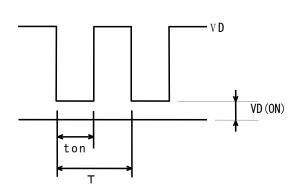
【Figure 2:測定回路図/Measure Circuit】



$$Ron = \frac{VD(ON)}{\overline{ID}} \times \frac{ton}{T}$$

端子説明/Terminal explanation

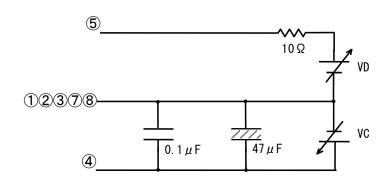
4 : Control 12378 : Source 5 : Drain

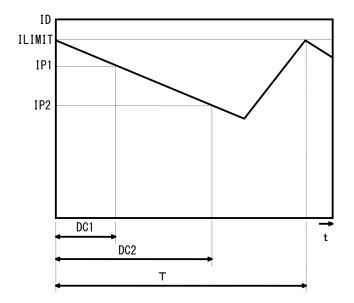


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【Figure 3:測定回路図/Measure Circuit】





$$ILIMIT = \frac{DC2 \cdot IP1 - DC1 \cdot IP2}{DC2 - DC1}$$

$$m = fOSC \cdot \frac{IP1 - IP2}{DC2 - DC1}$$

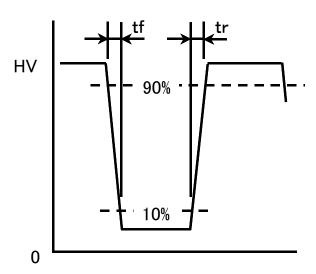
端子説明/Terminal explanation

4 : Control 12378 : Source 5 : Drain

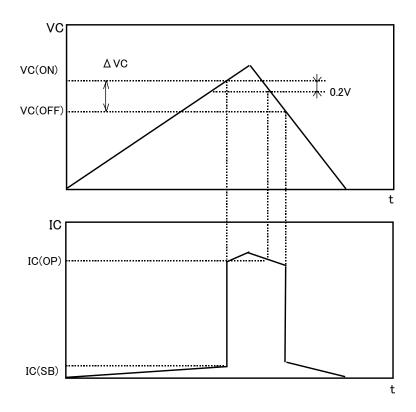
\*DC1, DC2は、VDをそれぞれVD1, VD2にしたときのデューティーサイクル(0 < DC1 < DC2 < MAXDC) DC1, DC2 is duty cycle when VD is VD1 and VD2, respectively.



[NOTE (1)]

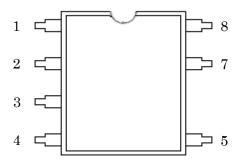


#### [NOTE (2)]



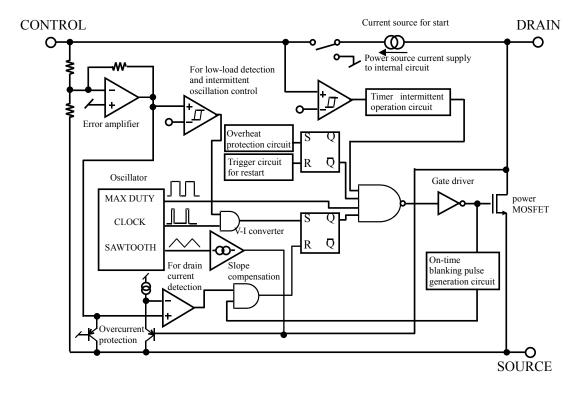
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【Figure 4:端子配置図/Pin Layout】



Pin No.	端子名/Terminal Name
1	Source
2	Source
3	Source
4	Control
5	Drain
6	-
7	Source
8	Source

【Figure 5:ブロック図/Block Figure】



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